

Title (en)

CIRCUIT AND A METHOD FOR THE PRODUCTION THEREOF

Title (de)

SCHALTUNGSANORDNUNG MIT EINEM DRUCKKONTAKT UND VERFAHREN ZU DEREN HERSTELLUNG

Title (fr)

CIRCUIT ET SON PROCEDE DE PRODUCTION

Publication

EP 1095404 A1 20010502 (DE)

Application

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Abstract (en)

[origin: WO0003437A1] According to the invention, a pressure contact (D) is arranged on a conducting region of the circuit in order to reinforce the connections of the circuit. Said pressure contact contains metal, e.g. copper, comprises an essentially planar upper surface which is situated above a passivation layer (S), and has flanks which are, to a large extent, essentially vertical. The metal is electrodeposited using a mask (P) which does not cover an area of the conducting region that is to be contacted, thus resulting in the production of the pressure contact (D). The electrodeposition process is concluded as long as the upper surface of the pressure contact (D) is situated underneath an upper surface of the mask (P). A conducting layer (L) which, for example, contains copper can be deposited on the conducting region in order to permit the application of a current for the electrodeposition process and can be deposited as a crystallization base.

IPC 1-7

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IPC 8 full level

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CPC (source: EP KR)

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